



Application Data Sheet
Application Information

Application type:: Regular
Subject matter:: Utility
CD-ROM or CD-R:: None
Number of CD disks:: 0
Number of copies of CDs:: 0
Sequence submission?:: No
Computer readable form (CRF)?:: No
Number of copies of CRF:: 0
Title:: Flip Chip Package With
Reinforced Bumps
Attorney docket number:: WANG3232/EM
Request for early publication?:: No
Request for non-publication?:: No
Suggested drawing figure:: 2
Total drawing sheets:: 2
Small entity?:: No

Applicant Information

Applicant authority type:: Inventor
Primary citizenship country:: Taiwan, R.O.C.
Status: Full capacity
Given name:: Sung-Fei
Middle name::
Family name:: WANG
City of Residence:: Kaohsiung
Country of residence:: Taiwan, R.O.C.

Street of mailing address:: No. 21, Alley 90, Lane 729,
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City of mailing address:: Kaohsiung
Country of mailing address:: Taiwan, R.O.C.
Postal or zip code of mailing
address::

Correspondence Information

Correspondence customer number:: 23364
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Representative Information

Representative customer number:: 23364

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority claimed::
Taiwan, R.O.C.	092109531	<u>04/23/2003</u>	Yes

Assignee Information

Assignee name:: Advanced Semiconductor
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Processing Zone
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